

BCR5PM-14L

Triac

Medium Power Use

REJ03G0307-0100

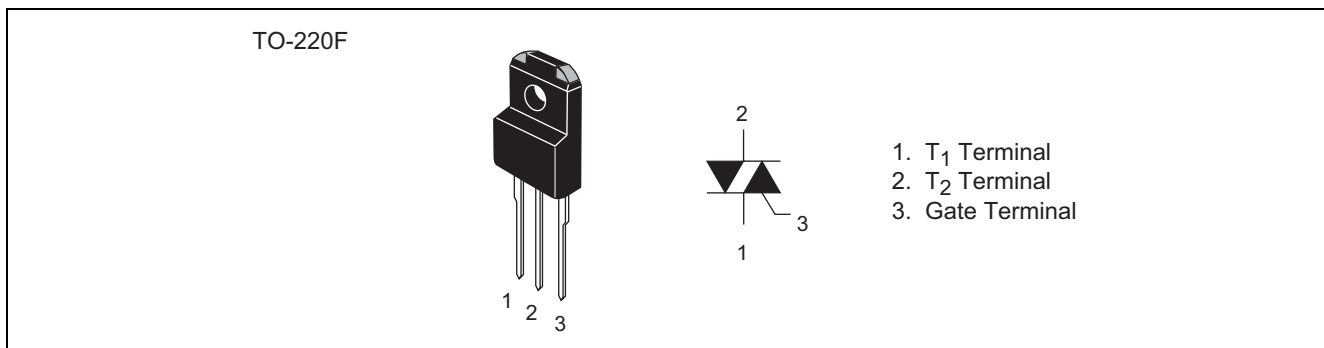
Rev.1.00

Aug.20.2004

Features

- $I_{T(RMS)}$: 5 A
- V_{DRM} : 700 V
- I_{FGTI} , I_{RGTI} , I_{RGTIII} : 30 mA
- V_{ISO} : 2000 V
- Insulated Type
- Planar Passivation Type
- UL Recognized : Yellow Card No. E223904
File No. E80271

Outline



Applications

Switching mode power supply, washing machine, small motor control, copying machine, electric heater control, and other general controlling devices

Maximum Ratings

| Parameter | Symbol | Voltage class | Unit |
|--|-----------|---------------|------|
| | | 14 | |
| Repetitive peak off-state voltage ^{Note1} | V_{DRM} | 700 | V |
| Non-repetitive peak off-state voltage ^{Note1} | V_{DSM} | 840 | V |

| Parameter | Symbol | Ratings | Unit | Conditions |
|--------------------------------|-------------|-------------|----------------------|--|
| RMS on-state current | I_T (RMS) | 5 | A | Commercial frequency, sine full wave 360° conduction, $T_c = 95^\circ\text{C}$ |
| Surge on-state current | I_{TSM} | 50 | A | 60Hz sinewave 1 full cycle, peak value, non-repetitive |
| I^2t for fusing | I^2t | 10.4 | A^2s | Value corresponding to 1 cycle of half wave 60Hz, surge on-state current |
| Peak gate power dissipation | P_{GM} | 3 | W | |
| Average gate power dissipation | $P_{G(AV)}$ | 0.3 | W | |
| Peak gate voltage | V_{GM} | 10 | V | |
| Peak gate current | I_{GM} | 2 | A | |
| Junction temperature | T_j | -40 to +125 | $^\circ\text{C}$ | |
| Storage temperature | T_{stg} | -40 to +125 | $^\circ\text{C}$ | |
| Mass | — | 2.0 | g | Typical value |
| Isolation voltage | Viso | 2000 | V | $T_a = 25^\circ\text{C}$, AC 1 minute, $T_1 \cdot T_2 \cdot G$ terminal to case |

Notes: 1. Gate open.

Electrical Characteristics

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test conditions |
|---|---------------|--------------|------|------|------------------------|---|
| Repetitive peak off-state current | I_{DRM} | — | — | 2.0 | mA | $T_j = 125^\circ\text{C}$, V_{DRM} applied |
| On-state voltage | V_{TM} | — | — | 1.8 | V | $T_c = 25^\circ\text{C}$, $I_{TM} = 7\text{ A}$, Instantaneous measurement |
| Gate trigger voltage ^{Note2} | I | V_{FGTI} | — | — | 1.5 | $T_j = 25^\circ\text{C}$, $V_D = 6\text{ V}$, $R_L = 6\ \Omega$, $R_G = 330\ \Omega$ |
| | II | V_{RGTI} | — | — | 1.5 | |
| | III | V_{RGTIII} | — | — | 1.5 | |
| Gate trigger current ^{Note2} | I | I_{FGTI} | — | — | 30 | $T_j = 25^\circ\text{C}$, $V_D = 6\text{ V}$, $R_L = 6\ \Omega$, $R_G = 330\ \Omega$ |
| | II | I_{RGTI} | — | — | 30 | |
| | III | I_{RGTIII} | — | — | 30 | |
| Gate non-trigger voltage | V_{GD} | 0.2 | — | — | V | $T_j = 125^\circ\text{C}$, $V_D = 1/2 V_{DRM}$ |
| Thermal resistance | $R_{th(j-c)}$ | — | — | 4.0 | $^\circ\text{C/W}$ | Junction to case ^{Note3} |
| Critical-rate of rise of off-state commutating voltage ^{Note4} | $(dv/dt)_c$ | 5 | — | — | $\text{V}/\mu\text{s}$ | $T_j = 125^\circ\text{C}$ |

Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

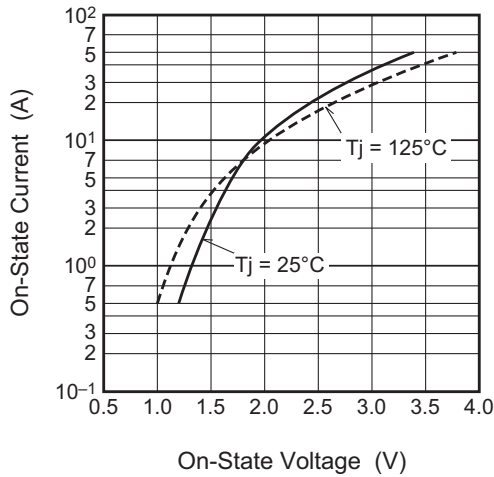
3. The contact thermal resistance $R_{th(c-f)}$ in case of greasing is 0.5°C/W .

4. Test conditions of the critical-rate of rise of off-state commutating voltage is shown in the table below.

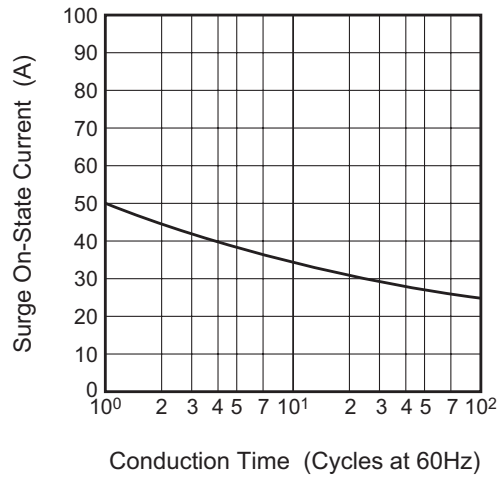
| Test conditions | Commutating voltage and current waveforms (inductive load) |
|---|--|
| 1. Junction temperature $T_j = 125^\circ\text{C}$ 2. Rate of decay of on-state commutating current $(di/dt)_c = -2.5\text{ A/ms}$ 3. Peak off-state voltage $V_D = 400\text{ V}$ | |

Performance Curves

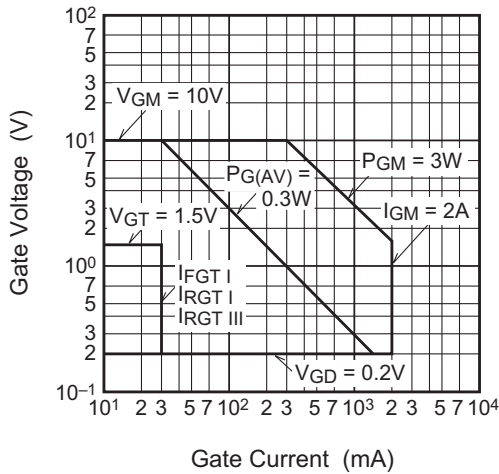
Maximum On-State Characteristics



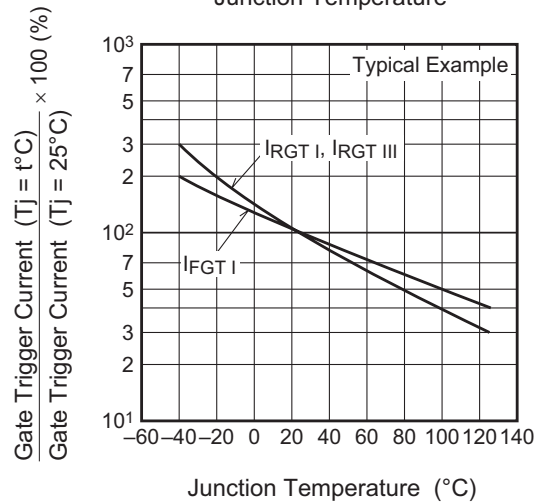
Rated Surge On-State Current



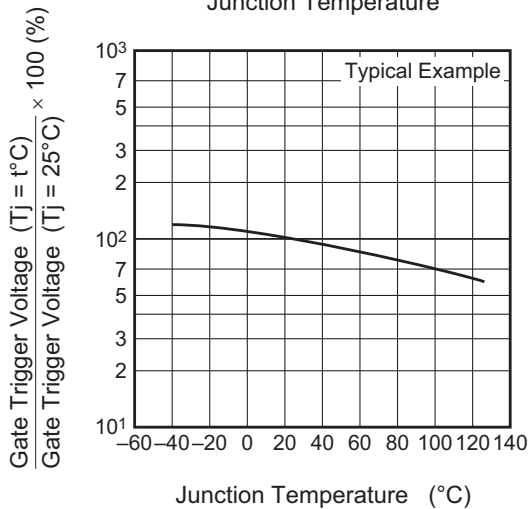
Gate Characteristics (I, II and III)



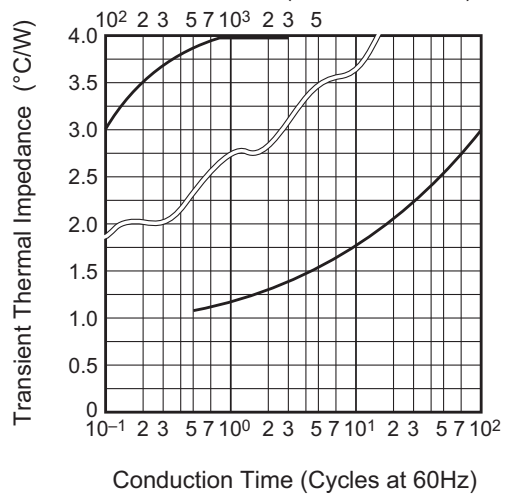
Gate Trigger Current vs. Junction Temperature

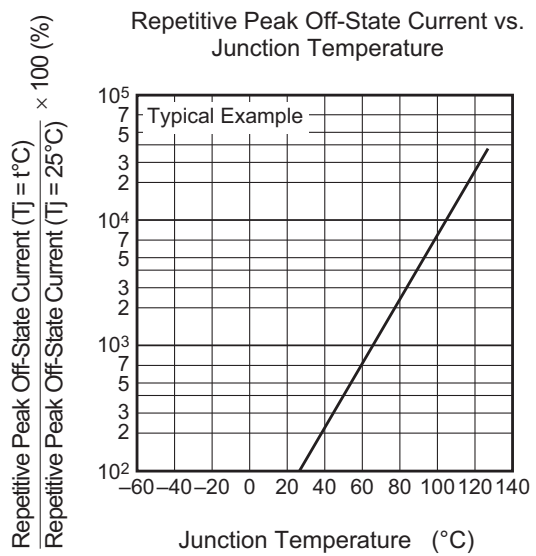
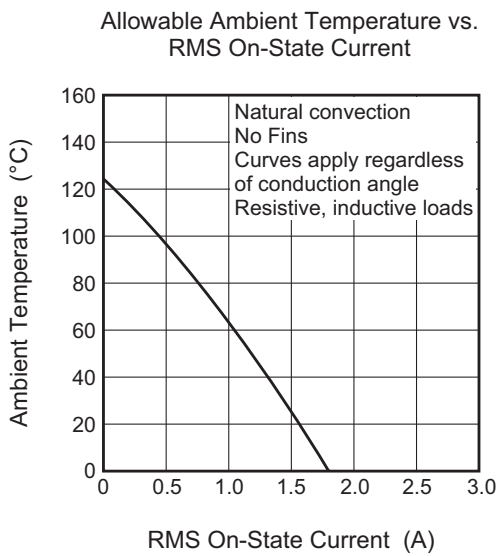
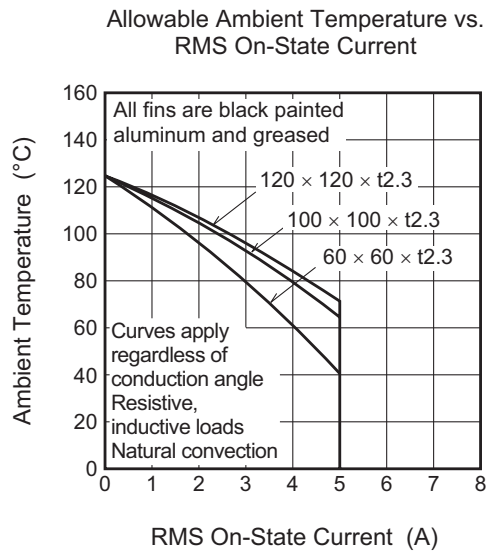
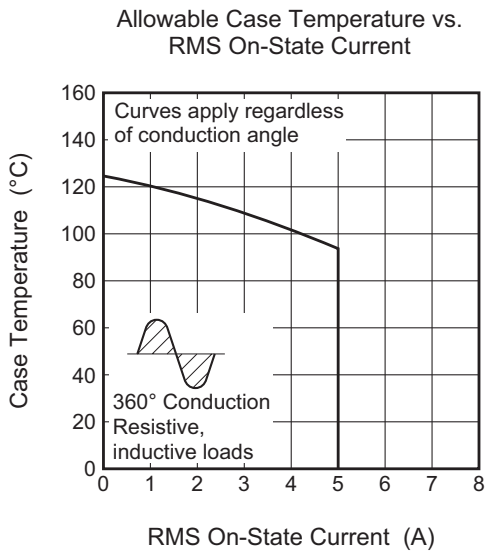
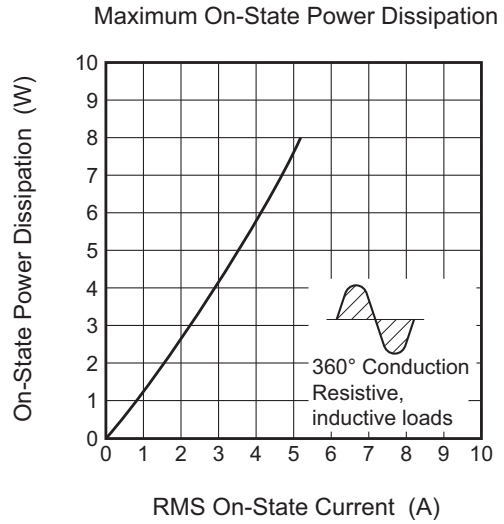
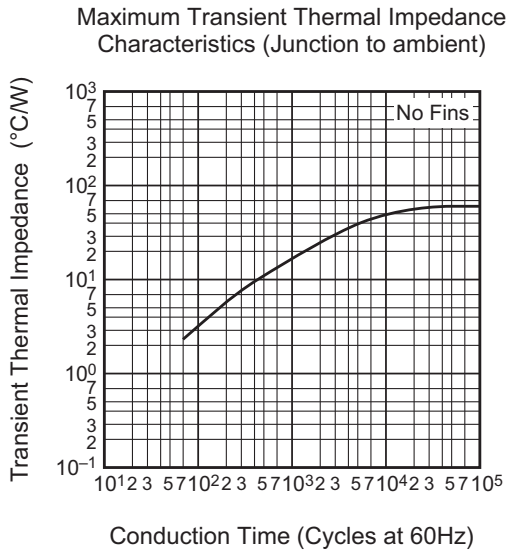


Gate Trigger Voltage vs. Junction Temperature

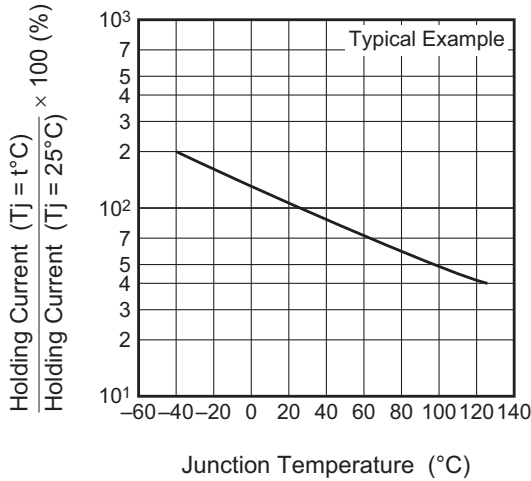


Maximum Transient Thermal Impedance Characteristics (Junction to case)

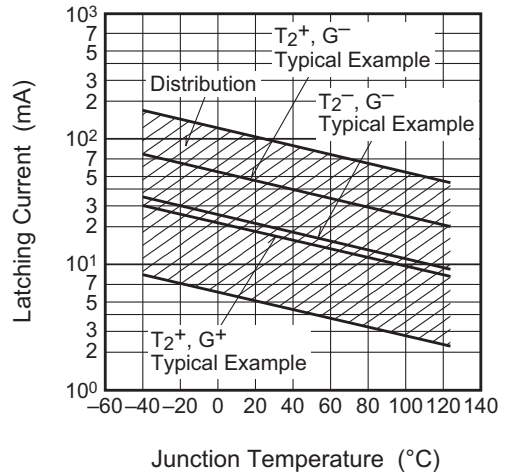




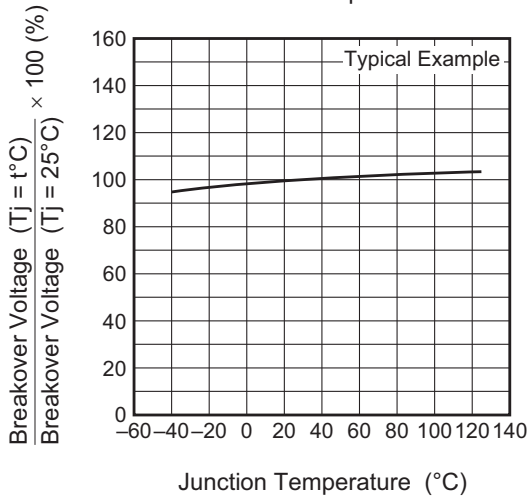
Holding Current vs. Junction Temperature



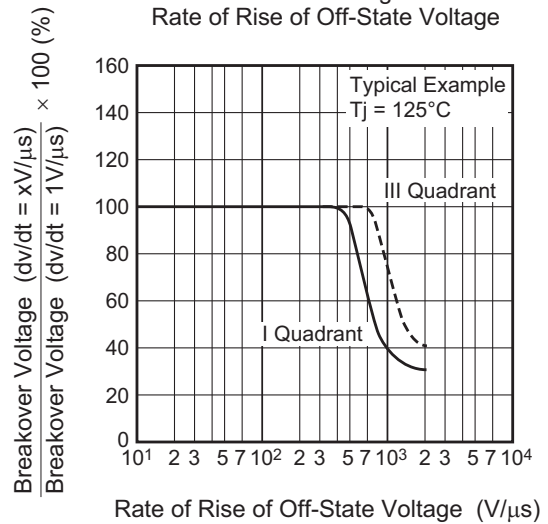
Latching Current vs. Junction Temperature



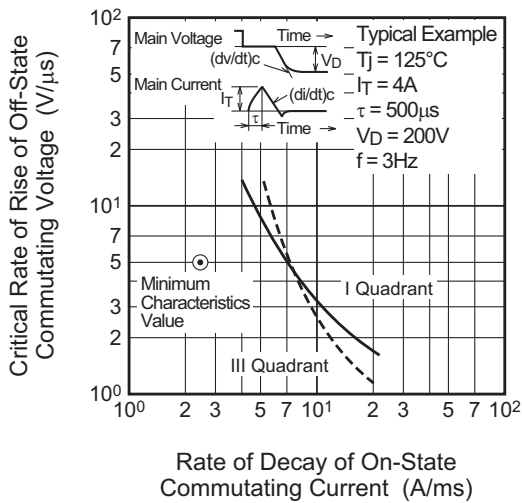
Breakover Voltage vs. Junction Temperature



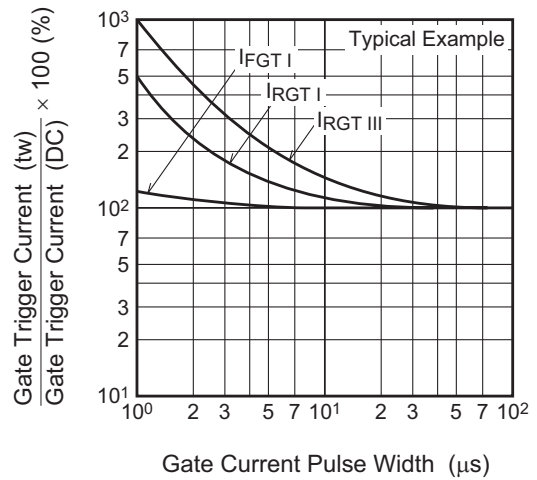
Breakover Voltage vs. Rate of Rise of Off-State Voltage



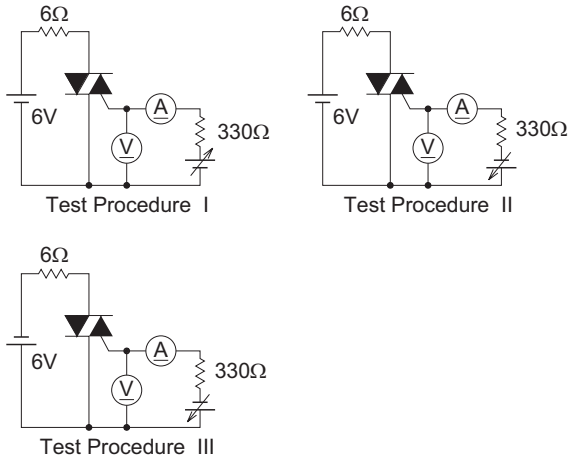
Commutation Characteristics



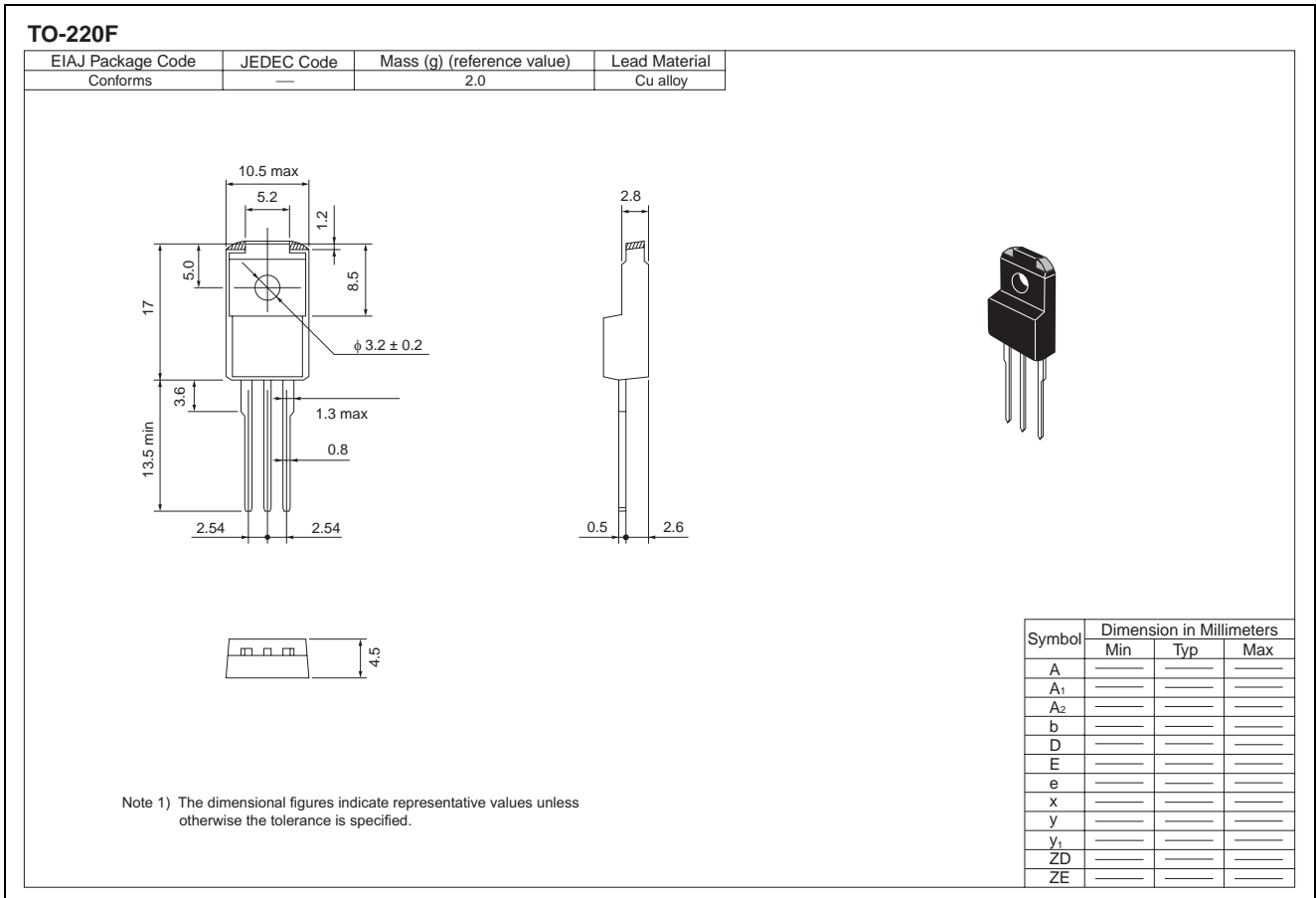
Gate Trigger Current vs. Gate Current Pulse Width



Gate Trigger Characteristics Test Circuits



Package Dimensions



Order Code

| Lead form | Standard packing | Quantity | Standard order code | Standard order code example |
|---------------|-------------------------|----------|----------------------------------|-----------------------------|
| Straight type | Vinyl sack | 100 | Type name +A | BCR5PM-14LA |
| Lead form | Plastic Magazine (Tube) | 50 | Type name +A – Lead forming code | BCR5PM-14LA-A8 |

Note : Please confirm the specification about the shipping in detail.

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